

Spec. No.: HL1209-4PPD5B

Issued Date: 2023-06-21

SPECIFICATION

Model Name: Monitor PD Photo diode

Model NO. : HL1209-4PPD5B

Customer No.:

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Approved by: Xie Zong Wu

Customer approved by: _____



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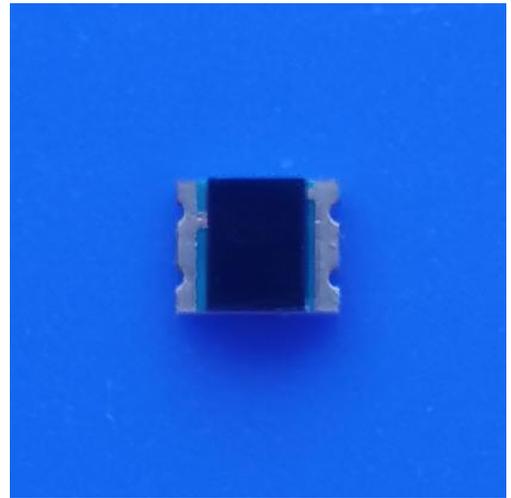
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Multi Emitters

HL1209-4PPD5B

■ Features

- $\Phi 500\mu\text{m}$ active area
- High responsibility
- Low dark current
- Low operating bias voltage
- -40°C to 85°C operation range
- 100% testing and inspection
- Customized chip dimension is available
- Excellent reliability: All chips have passed the qualification requirements as specified by Telcordia -GR-468-CORE



■ Applications

- Back facet laser power monitoring

Name	Model	Resin Color	Package
MPD	HL1209-4PPD5B	Black	4Pin, COB

■ Absolute Maximum Ratings

($T_a = 25^{\circ}\text{C}$)

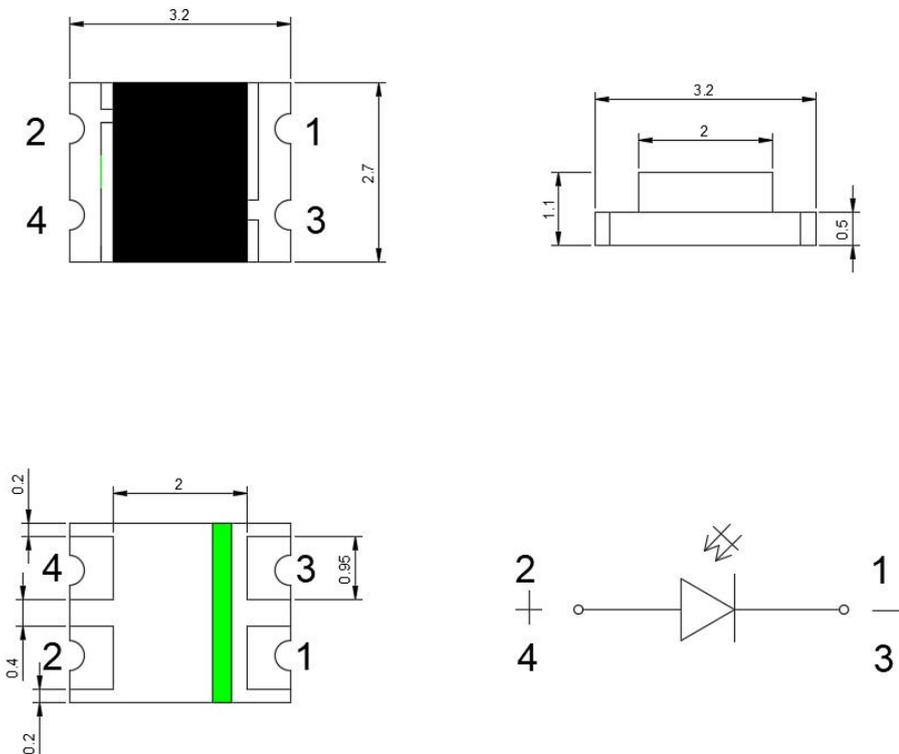
Parameter	Symbol	Max.	Unit	Note
Optical Power Input	P_{in}	10	mW	---
Forward Current	I_F	10	mA	---
Reverse Current	I_R	5	mA	---
Reverse Voltage	V_R	30	V	---
Operating Temperature	T_{opr}	$-40 \sim +85$	$^{\circ}\text{C}$	---
Storage Temperature	T_{stg}	$-45 \sim +125$	$^{\circ}\text{C}$	---
Soldering Temperature	T_{S01}	260	$^{\circ}\text{C}$	260 $^{\circ}\text{C}$ for 3 Seconds

■ Electrical/Optical Characteristics

(Ta= 25°C)

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Reverse Breakdown Voltage	V_{BR}	35	--	--	V	$I_R=10\mu A$
Dark Current	I_D	--	0.5	2.5	nA	$V_R=5V$
Responsivity	R_e	0.9	1.0	--	A/W	$\lambda=1310nm, P_{in}=0.5mW, V_R=1.0V$
		1.0	1.05	--		$\lambda=1550nm, P_{in}=0.5mW, V_R=1.0V$
Response Spectrum	λ	900	--	1700	nm	$I_F=20mA$
Capacitance	C_j	--	12	15	pF	$F=1MHz, V_R=5V$

■ Dimension:



■ Storage and Soldering Condition

Please read the following notes before using the product: 使用本产品前请阅读以下说明:

1. Over-current-proof 过电流保护

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

客户必须用电阻器保护；否则微小的电压变化会引起较大的电流变化（将会发生烧坏）。

2. Storage 储存

2.1 Do not open moisture proofs bag before the products are ready to use.

2.2 在产品准备使用前不要打开防潮袋

2.3 Before opening the package, the LEDs should be kept at 30°C or less and 85% RH or less. 打开包装前, LED应保持在30°C以下或小于85%湿度

2.4 The LEDs should be used within a year. 未拆包的LED应在一年内使用.

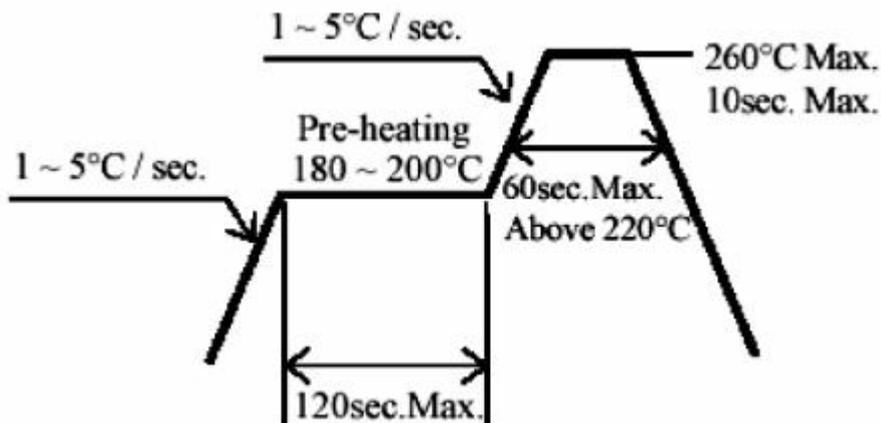
2.5 After opening the package, the LEDs should be kept at 30°C or less and 65% RH or less. 打开包装后, LED应保持在温度30°C以下或湿度小于等于65%。

2.6 The LEDs should be used within 4 weeks after opening the package. 打开包装后,LED应在4周内使用 If the moisture adsorbent material (silica gel) has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. 如果干燥剂挥发完或LED已经超过存储时间, 应采用下列条件进行烘烤处理。

Baking treatment: 65±5°C for 24 hours. 烘烤处理65±5°C 24小时

3. Soldering Condition 焊接条件

3.1 Pb-free solder temperature profile 无铅焊料温度分布



3.2 When soldering, do not put stress on the LEDs during heating. 焊接时, 加热期间不要对按压LED.

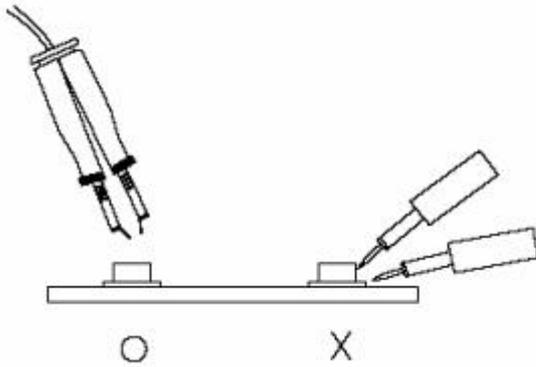
3.3 After soldering, do not warp the circuit board. 焊接后, 不要扭曲电路板

4. Soldering Iron 烙铁焊接

Each terminal is to go to the tip of soldering iron temperature less than 310°C for 2 seconds. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder. 烙铁温度小于310°C，焊接时间少于2秒，留出两秒以上的间隔，对每个端子进行焊接。请小心焊接，因为产品的损坏通常在手焊时开始。

5. Repairing 返工

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing. LED已焊接完成后不应返工。当必须要返工时，应使用双头烙铁（如下图）。应事先确认LED的特性是否会因修复而损坏或不会被损坏。



修订记录

项次	日期	内 容	版本号
1	2023-06-21	新发行	Ver.01